



MIKE DEWINE
GOVERNOR OF OHIO



August 14, 2023

Eric Smith
Director
Office of Innovation and Entrepreneurship
U.S. Department of Commerce
Economic Development Administration
1401 Constitution Avenue, NW
Suite 71014
Washington, DC 20230

Dear Director Smith,

As Governor of Ohio, I am pleased to support and showcase the innovative technology being developed throughout our great state. Technological advancements being made right here in Ohio are helping to shape a bright future for our state and our nation.

The proposed Tech Hub project by the **Silicon Heartland-Appalachia Regional Engine for Semiconductors (SHARES) Consortium** will help to further establish Ohio as *the* place to research, develop, and manufacture critical semiconductors and microelectronics that power our world. Just last September, Intel broke ground on their most recent “fab” outside of Columbus. This \$20 billion private investment was the largest in Ohio history, and the SHARES Consortium has an unparalleled opportunity to leverage this investment to advance the United States’ semiconductor industry. Accordingly, I am proud to offer my strong support for the Silicon Heartland-Appalachia Regional Engine for Semiconductors Consortium application.

The Tech Hubs Program creates a unique opportunity to drive regional technological innovation and make critical investments in our nation’s future. Thank you for your consideration, and I look forward to the opportunity to help ensure that this investment is a success.

Very respectfully yours,

A handwritten signature in blue ink that reads "Mike DeWine".

Mike DeWine
Governor